

High Performance Press Pads



For Lamination of Rigid Multilayer and Flexible Circuits

PACOPADS® are a line of press pads specifically engineered to improve the process of laminating rigid multi-layer and flexible Printed Circuit Boards. They serve two primary functions: to accurately Control heat input and to Equalize the pressure applied to the panel surface.

LAMINATION PROCESS ADVANTAGES

- **Control of Heat Rise**
PACOPADS perform this function with totally predictable and reproducible results due to their uniform fiber distribution and tightly controlled thickness and weight specifications.
- **Equalization of Pressure Throughout the Pressure Load**
Use of PACOPADS eliminates air voids, inner-layer slippage and White corners or edges. PACOPADS also reduce dielectric thickness variations, image and glass cloth transfer, and obviate the potential of low-pressure prepreg blisters.
- **3-Dimensional Conformance**
PACOPADS eliminate X-Y-Z axis stress which precludes Cover-layer voids and circuit distortion. At the same time, PACOPADS improve cavity fill, and adhesive flow control in the manufacture of Flex, Rigid-flex, and Heat Sink Circuit Boards.

PACOPADS® PRESS PAD FEATURES

- Proven worldwide performance since 1986.
- Operating temperature of 475°F/246°C for six hours.
- Three standard thicknesses of .035" (.89mm), .055" (1.4mm), and .085" (2.2mm) for custom Heat Input Control and optimal Pressure Equalization.
- Extremely low moisture to reduce liquid build-up in vacuum systems.
- Uniform fiber formation and distribution for unmatched pressure equalization, micro Z-axis conformance and repeatable, consistent Heat Rise.

- Low fiber dusting and contamination.
- No resinous binders or fillers, essentially sulfur free, with no odor or solvents to pollute vacuum systems or the work environment.
- Environmentally friendly – suitable for re-pulping, land fill disposal or incineration.

TECHNICAL DESCRIPTION

PACOPADS are a unique, cellulosic-based product, engineered specifically to meet the performance requirements of both Rigid Multilayer and Flexible Printed Circuit Board manufacture. PACOPADS are manufactured on a highly specialized paper machine, using virgin fibers, that guarantees a low density profile consistent across the entire area of the sheet.

PACOPADS are vastly superior to commodity grade papers which varies significantly in weight, thickness, hard spots, contaminants, and moisture.

AVAILABILITY

PACOPADS are always available in custom-sized sheets [with or without tooling holes] for “Just-In-Time” delivery through exclusive local Distributors around the world from locally available stocks.

Other complimentary Lamination Assist Product offerings include:

RELEASE PRODUCTS



PRESS PADS AND CONFORMABLES



APPLICATION SPECIFIC



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